Appl. No. 09/753,188 Amdt. dated Sept. 18, 2003 Reply to Office Action of June 18, 2003

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-38 (Canceled)

Claim 39 (Previously presented): Method of mounting an interconnection element to a terminal of an electronic component, comprising:

attaching an elongate element of a first material to a terminal of an electronic component; shaping the elongate element with a shaping tool; and

overcoating the elongate element with a second material which has a higher yield strength than the first material, in an amount sufficient for imparting a desired resiliency to the interconnection element, whereby the interconnection element after the overcoating step is substantially stiffer than the elongate element prior to the overcoating step.

Claim 40 (Original): Method, according to claim 39, further comprising:

while overcoating the elongate element, overcoating at least a portion of an exposed surface of the terminal with the second material.

Claims 41-53 (Canceled)